

**TOSHIBA ANNOUNCES NEW DESERIALIZER DISPLAY BRIDGE CHIP FOR
MOBILE DEVICES**

*Bridge Chip Connects Advanced Baseband or Application Processors to High
Resolution Displays with Parallel Interfaces*

Mobile World Congress, February 15, 2010 – [Toshiba Electronics Europe](#) today announced a new deserializer display bridge chip (TC358762XBG). The device connects the baseband or application processors used in smart phones, which use Mobile Industry Processor Interface-Display Serial Interfaces (MIPI®-DSI), to displays with legacy parallel interfaces. This capability allows OEMs to implement the power of an advanced mobile processor in other mobile applications beyond smart phones where high-resolution displays with parallel interfaces are more commonly used. This deserializer bridge chip, along with three other bridge chips announced today, is the latest addition to the Toshiba Mobile Product Initiative portfolio of mobile peripheral devices designed to help customers implement more advanced technologies in their handheld products.

Toshiba's mobile peripheral devices are connectivity chipsets that enable flexibility in mechanical design, a broader selection of major components such as displays and cameras, reduction in power consumption, and reduction in EMI issues in handheld devices such as smart phones, mobile internet devices, netbooks, smartbooks, eBooks, and personal media and navigation devices. The TC358762XBG deserializer bridge chip uses the MIPI high-speed serial interface to deliver the large data bandwidth needed for displaying high-resolution video content.

The TC358762XBG deserializer bridge chip is targeted for use with high-resolution display panels HVGA, VGA, WVGA, qHD, and XGA. It supports video input frame rates of up to 60 frames per second for XGA and 30 frames per second for 720P. It uses a dual-lane DSI receiver that is bi-directional at lane 0 and supports data rates of up to 800 Mbps per lane for total data bandwidth of 1.6Gbps. The chip's DPI (display port interface) host has a bus speed of up to 70 MHz burst rate. The device can also be used to connect pico projectors to baseband and application processors to enable embedded digital projector applications in mobile devices.

Availability

Engineering samples of the TC358762XBG deserializer bridge chip are available now, with mass production scheduled to begin in March 2010.

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About Toshiba

Toshiba Electronics Europe (TEE) is the European electronic components business of Toshiba Corporation, which is ranked among the world's largest semiconductor vendors. TEE offers one of the industry's broadest IC and discrete product lines including high-end memory, microcontrollers, ASICs, ASSPs and display products for automotive, multimedia, industrial, telecoms and networking applications. The company also has a wide range of power semiconductor solutions. TEE was formed in 1973 in Neuss, Germany, providing design, manufacturing, marketing and sales and now has headquarters in Düsseldorf, Germany, with subsidiaries in France, Italy, Spain, Sweden and the United Kingdom. TEE employs approximately 300 people in Europe. Company president is Mr. Hitoshi Otsuka.

Toshiba Corporation is a world leader and innovator in pioneering high technology, a diversified manufacturer and marketer of advanced electronic and electrical products spanning information & communications systems; digital consumer products; electronic devices and components; power systems, including nuclear energy; industrial and social infrastructure systems; and home appliances. Founded in 1875, Toshiba today operates a global network of more than 740 companies, with 199,000 employees worldwide and annual sales surpassing US\$73 billion.

For more information visit Toshiba Electronics Europe's web site at www.toshiba-components.com

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February 2010

Ref. 5998/A